Complementary Power Transistors

DPAK For Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Straight Lead Version in Plastic Sleeves ("1" Suffix)
- Lead Formed Version in 16 mm Tape and Reel ("T4" Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- Epoxy Meets UL 94, V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

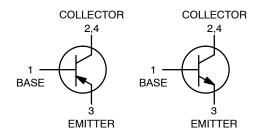


ON Semiconductor®

http://onsemi.com

SILICON POWER TRANSISTORS 3 AMPERES 40 AND 100 VOLTS 15 WATTS

COMPLEMENTARY



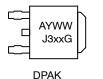


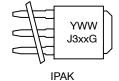
DPAK CASE 369C STYLE 1



IPAK CASE 369D STYLE 1

MARKING DIAGRAMS





A = Site Code
Y = Year
WW = Work Week
xx = 1, 1C, 2, or 2C
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage MJD31, NJVMJD31T4G, MJD32, NJVMJD32T4G MJD31C, NJVMJD31CG, NJVMJD31CRLG, NJVMJD31CT4G, MJD32C, NJVMJD32CG, NJVMJD32CT4G	V _{CEO}	40 100	Vdc
Collector-Base Voltage MJD31, NJVMJD31T4G, MJD32, NJVMJD32T4G MJD31C, NJVMJD31CG, NJVMJD31CRLG, NJVMJD31CT4G, MJD32C, NJVMJD32CG, NJVMJD32CT4G	V _{CB}	40 100	Vdc
Emitter-Base Voltage	V _{EB}	5.0	Vdc
Collector Current – Continuous	Ic	3.0	Adc
Collector Current - Peak	I _{CM}	5.0	Adc
Base Current	I _B	1.0	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	15 0.12	W W/°C
Total Power Dissipation @ T _A = 25°C Derate above 25°C	P _D	1.56 0.012	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C
ESD – Human Body Model	НВМ	3B	V
ESD – Machine Model	MM	С	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	8.3	°C/W
Thermal Resistance, Junction-to-Ambient*	$R_{ hetaJA}$	80	°C/W
Lead Temperature for Soldering Purposes	Tı	260	°C

^{*}These ratings are applicable when surface mounted on the minimum pad sizes recommended.

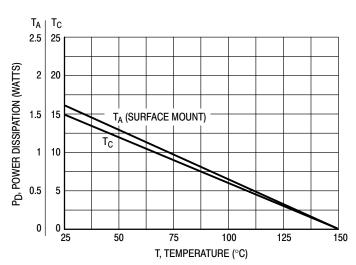
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Sustaining Voltage (Note 1) (I _C = 30 mAdc, I _B = 0) MJD31, NJVMJD31T4G, MJD32, NJVMJD32T4G MJD31C, NJVMJD31CG, NJVMJD31CRLG, NJVMJD31CT4G, MJD32C, NJVMJD32CG, NJVMJD32CT4G	V _{CEO(sus)}	40 100	-	Vdc
Collector Cutoff Current $ (V_{\text{CE}} = 40 \text{ Vdc, I}_{\text{B}} = 0) \\ \text{MJD31, NJVMJD31T4G, MJD32, NJVMJD32T4G} \\ (V_{\text{CE}} = 60 \text{ Vdc, I}_{\text{B}} = 0) \\ \text{MJD31C, NJVMJD31CG, NJVMJD31CRLG, NJVMJD31CT4G,} \\ \text{MJD32C, NJVMJD32CG, NJVMJD32CT4G} $	I _{CEO}	-	50 50	μAdc
Collector Cutoff Current (V _{CE} = Rated V _{CEO} , V _{EB} = 0)	ICES	-	20	μAdc
Emitter Cutoff Current (V _{BE} = 5 Vdc, I _C = 0)	I _{EBO}	-	1	mAdc
ON CHARACTERISTICS (Note 1)				
DC Current Gain	h _{FE}	25 10	_ 50	
Collector–Emitter Saturation Voltage (I _C = 3 Adc, I _B = 375 mAdc)	V _{CE(sat)}	-	1.2	Vdc
Base-Emitter On Voltage ($I_C = 3$ Adc, $V_{CE} = 4$ Vdc)	V _{BE(on)}	-	1.8	Vdc
DYNAMIC CHARACTERISTICS				
Current Gain – Bandwidth Product (Note 2) (I _C = 500 mAdc, V _{CE} = 10 Vdc, f _{test} = 1 MHz)	f _T	3	-	MHz
Small–Signal Current Gain (I _C = 0.5 Adc, V _{CE} = 10 Vdc, f = 1 kHz)	h _{fe}	20		

^{1.} Pulse Test: Pulse Width \leq 300 $\mu s,$ Duty Cycle \leq 2%.

^{2.} $f_T = |h_{fe}| \cdot f_{test}$.

TYPICAL CHARACTERISTICS



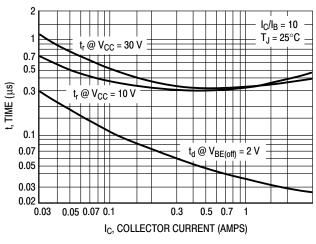
 R_C SCOPE R_C R_C

 R_B and R_C Varied to obtain desired current levels D_1 Must be fast recovery type, e.g.: $1 N5825 \ \text{USED ABOVE} \ I_B \approx 100 \ \text{mA} \\ \text{MSD6}100 \ \text{USED BELOW} \ I_B \approx 100 \ \text{mA} \\ \text{REVERSE ALL POLARITIES FOR PNP.}$

V_{CC} + 30 V

Figure 1. Power Derating

Figure 2. Switching Time Test Circuit



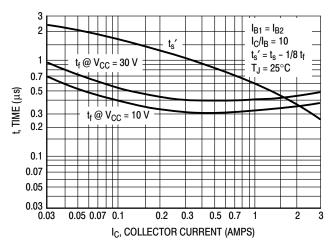


Figure 3. Turn-On Time

Figure 4. Turn-Off Time

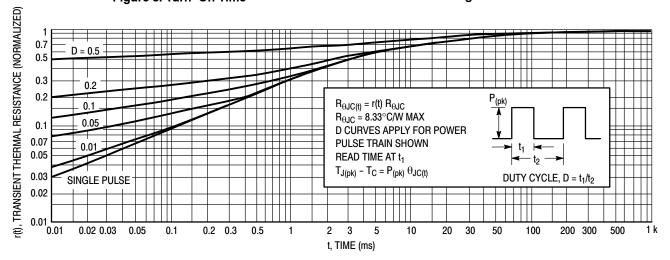
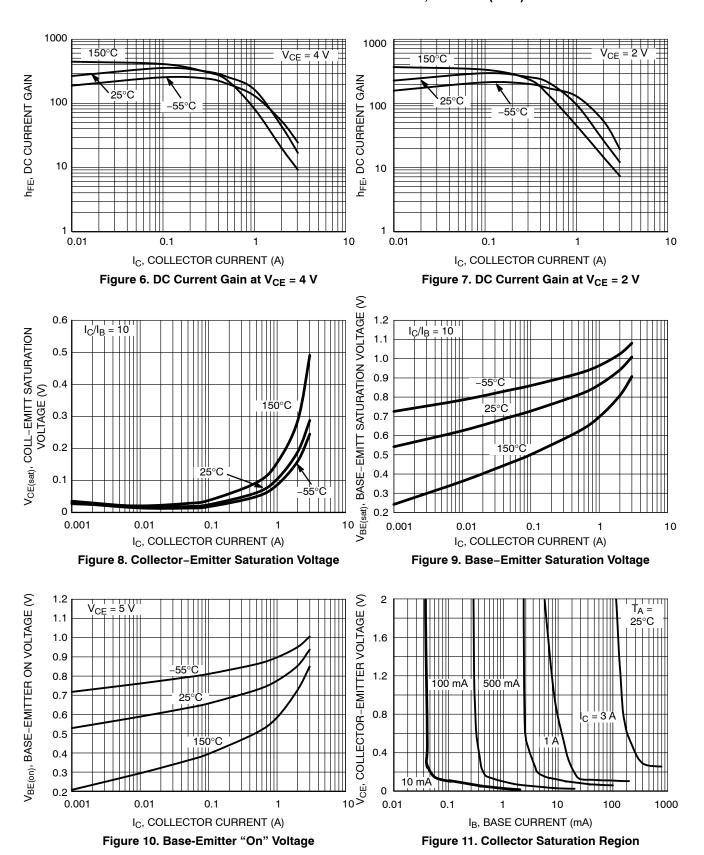


Figure 5. Thermal Response

TYPICAL CHARACTERISTICS - MJD31, MJD31C (NPN)



TYPICAL CHARACTERISTICS - MJD31, MJD31C (NPN)

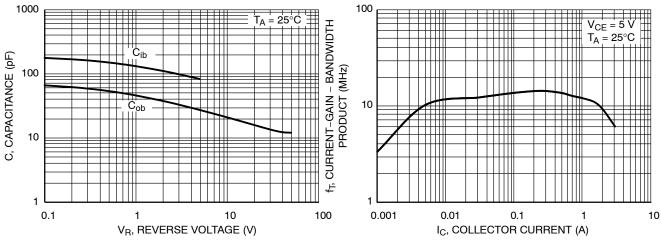


Figure 12. Capacitance

Figure 13. Current-Gain-Bandwidth Product

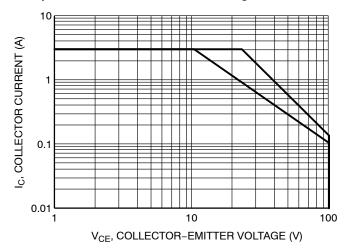
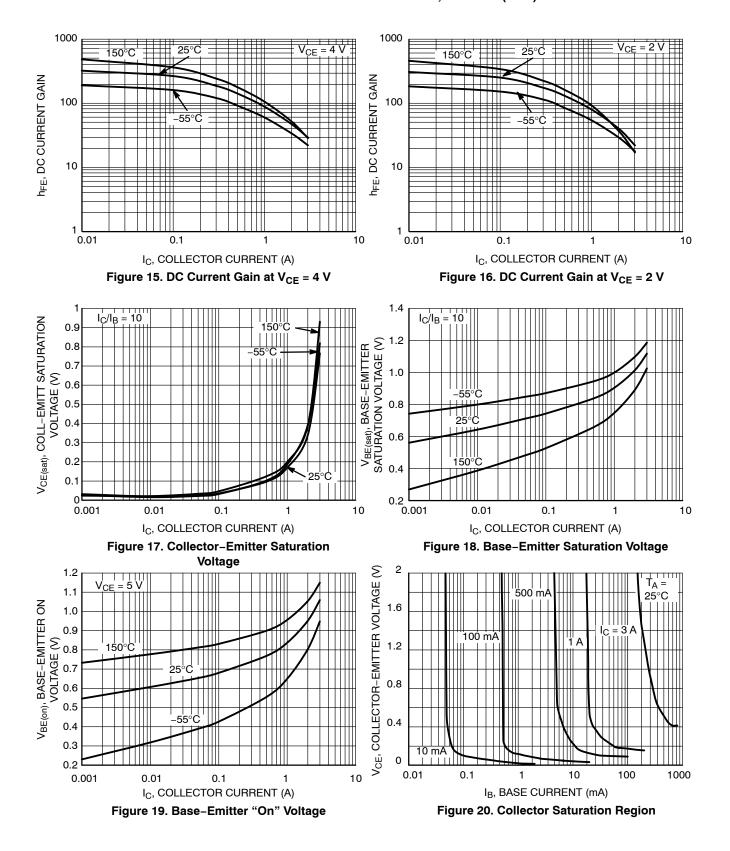


Figure 14. Safe Operating Area

TYPICAL CHARACTERISTICS - MJD32, MJD32C (PNP)



TYPICAL CHARACTERISTICS

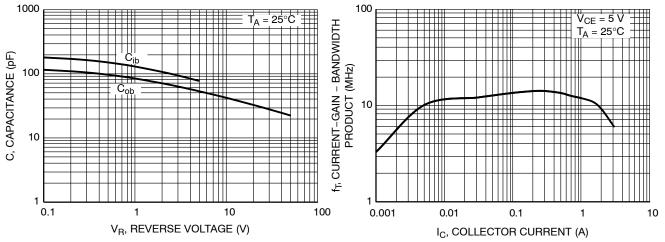


Figure 21. Capacitance

Figure 22. Current-Gain-Bandwidth Product

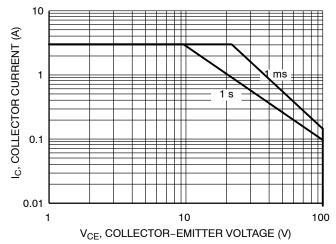


Figure 23. Safe Operating Area

ORDERING INFORMATION

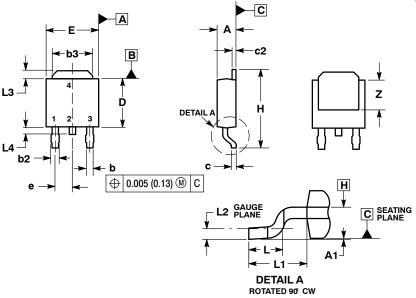
Device	Package Type	Package	Shipping [†]
MJD31CG	DPAK (Pb-Free)	369C	75 Units / Rail
NJVMJD31CG*	DPAK (Pb-Free)	369C	75 Units / Rail
MJD31C1G	IPAK (Pb-Free)	369D	75 Units / Rail
MJD31CRLG	DPAK (Pb-Free)	369C	1,800 / Tape & Reel
NJVMJD31CRLG*	DPAK (Pb-Free)	369C	1,800 / Tape & Reel
MJD31CT4G	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD31CT4G*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
MJD31T4G	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD31T4G*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
MJD32CG	DPAK (Pb-Free)	369C	75 Units / Rail
NJVMJD32CG*	DPAK (Pb-Free)	369C	75 Units / Rail
MJD32CRLG	DPAK (Pb-Free)	369C	1,800 / Tape & Reel
MJD32CT4G	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD32CT4G*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
MJD32RLG	DPAK (Pb-Free)	369C	1,800 / Tape & Reel
MJD32T4G	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD32T4G*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

DPAK CASE 369C ISSUE D



NOTES:

- OTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCHES.

- 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.

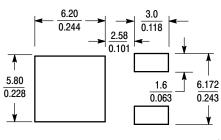
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

STYLE 1:

PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

SOLDERING FOOTPRINT*

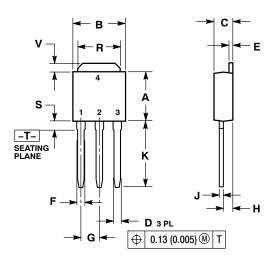


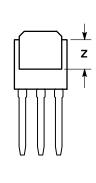
mm_ SCALE 3:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

IPAK CASE 369D **ISSUE C**





- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.245	5.97	6.35	
В	0.250	0.265	6.35	6.73	
С	0.086	0.094	2.19	2.38	
D	0.027	0.035	0.69	0.88	
Е	0.018	0.023	0.46	0.58	
F	0.037	0.045	0.94	1.14	
G	0.090 BSC		2.29	BSC	
Н	0.034	0.040	0.87 1.01		
J	0.018	0.023	0.46	0.58	
K	0.350	0.380	8.89	9.65	
R	0.180	0.215	4.45	5.45	
S	0.025	0.040	0.63	1.01	
٧	0.035	0.050	0.89	1.27	
Z	0.155		3.93		

STYLE 1:

PIN 1. BASE

- COLLECTOR
- 3. EMITTER
- COLLECTOR

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